

BSP220

P-channel enhancement mode vertical D-MOS transistor

Data sheet	
status	Product specification
date of issue	April 1991

FEATURES

- Low $R_{DS(on)}$
- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown.

DESCRIPTION

P-channel enhancement mode vertical D-MOS transistor in a miniature SOT223 envelope and intended for use in relay, high-speed and line transformer drivers.

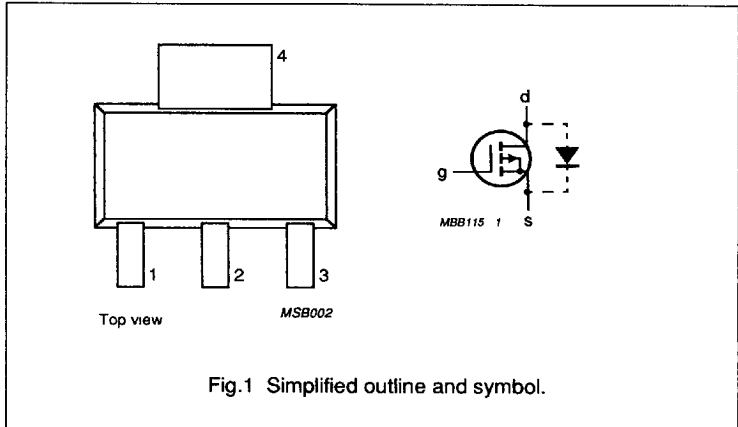
PINNING - SOT223

PIN	DESCRIPTION
1	gate
2	drain
3	source
4	drain

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
$-V_{DS}$	drain-source voltage		200	V
$-I_D$	drain current	DC value	225	mA
$R_{DS(on)}$	drain-source on-resistance	$-I_D = 200 \text{ mA}$ $-V_{GS} = 10 \text{ V}$	12	Ω
$-V_{GS(th)}$	gate-source threshold voltage		2.8	V

PIN CONFIGURATION



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LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$-V_{DS}$	drain-source voltage		–	200	V
$\pm V_{GSO}$	gate-source voltage	open drain	–	20	V
$-I_D$	drain current	DC value	–	225	mA
$-I_{DM}$	drain current	peak value	–	600	mA
P_{tot}	total power dissipation	up to $T_{amb} = 25\text{ }^\circ\text{C}$ (note 1)	–	1.5	W
T_{stg}	storage temperature range		–65	150	$^\circ\text{C}$
T_J	junction temperature		–	150	$^\circ\text{C}$

Note

- Device mounted on an epoxy printed-circuit board 40 x 40 x 1.5 mm; mounting pad for the drain lead minimum 6 cm².

THERMAL RESISTANCE

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ J-a}$	from junction to ambient (note 1)	83.3	K/W

Note

- Device mounted on an epoxy printed-circuit board 40 x 40 x 1.5 mm; mounting pad for the drain lead minimum 6 cm².

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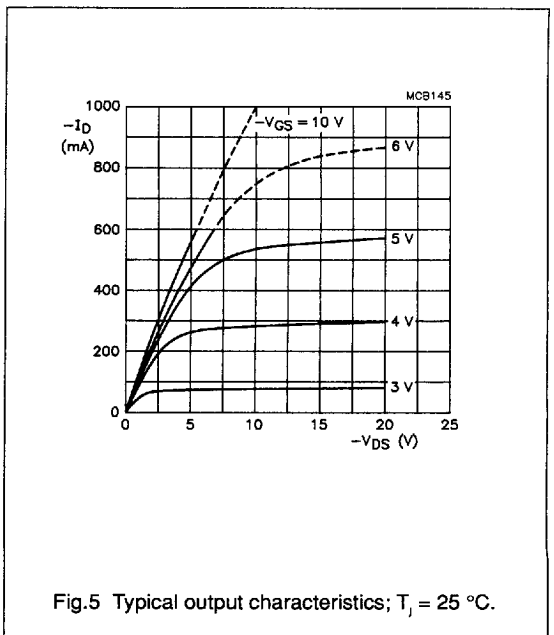
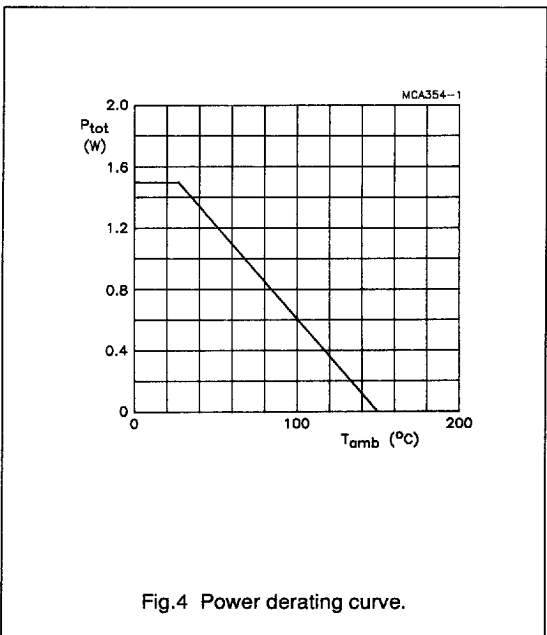
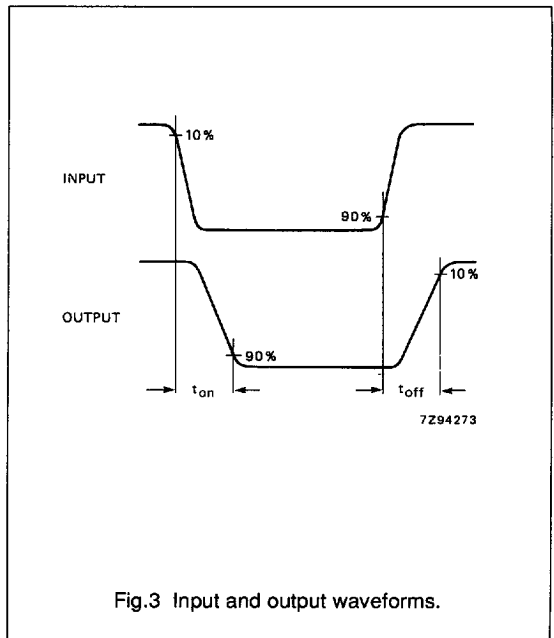
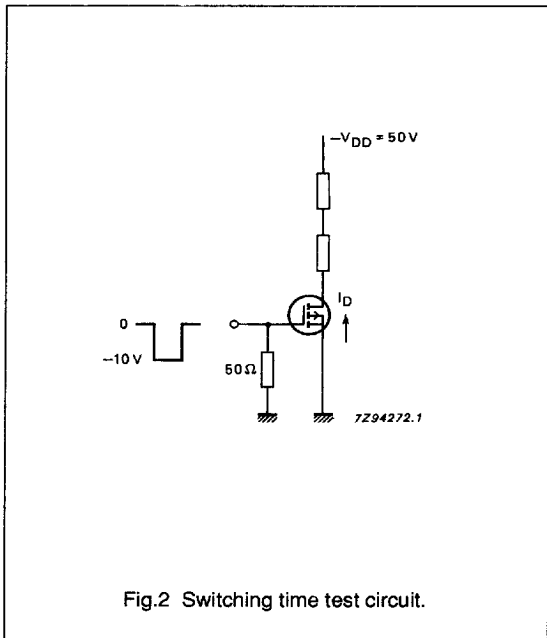
CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$-V_{(BR)DSS}$	drain-source breakdown voltage	$-I_D = 10\ \mu\text{A}$ $V_{GS} = 0$	200	—	—	V
$-I_{DSS}$	drain-source leakage current	$-V_{DS} = 160\ \text{V}$ $V_{GS} = 0$	—	—	1	μA
$\pm I_{GSS}$	gate-source leakage current	$\pm V_{GS} = 20\ \text{V}$ $V_{DS} = 0$	—	—	100	nA
$-V_{GS(th)}$	gate-source threshold voltage	$-I_D = 1\ \text{mA}$ $V_{GS} = V_{DS}$	0.8	—	2.8	V
$R_{DS(on)}$	drain-source on-resistance	$-I_D = 200\ \text{mA}$ $-V_{GS} = 10\ \text{V}$	—	10	12	Ω
$ Y_{fs} $	transfer admittance	$-I_D = 200\ \text{mA}$ $-V_{DS} = 25\ \text{V}$	100	200	—	mS
C_{iss}	input capacitance	$-V_{DS} = 25\ \text{V}$ $V_{GS} = 0$ $f = 1\ \text{MHz}$	—	65	90	pF
C_{oss}	output capacitance	$-V_{DS} = 25\ \text{V}$ $V_{GS} = 0$ $f = 1\ \text{MHz}$	—	20	30	pF
C_{rss}	feedback capacitance	$-V_{DS} = 25\ \text{V}$ $V_{GS} = 0$ $f = 1\ \text{MHz}$	—	6	15	pF
Switching times (see Figs 2 and 3)						
t_{on}	turn-on time	$-I_D = 250\ \text{mA}$ $-V_{DD} = 50\ \text{V}$ $-V_{GS} = 0\ \text{to}\ 10\ \text{V}$	—	5	20	ns
t_{off}	turn-off time	$-I_D = 250\ \text{mA}$ $-V_{DD} = 50\ \text{V}$ $-V_{GS} = 0\ \text{to}\ 10\ \text{V}$	—	20	30	ns

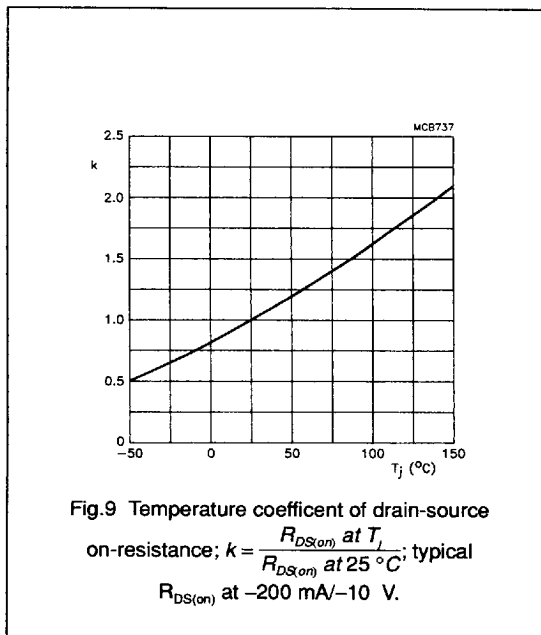
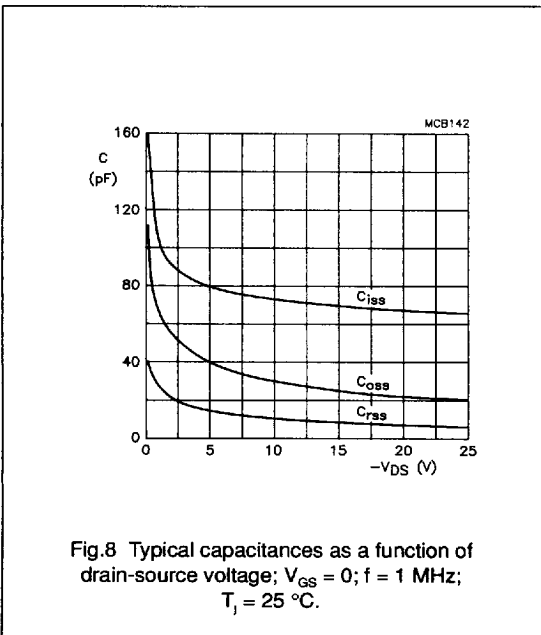
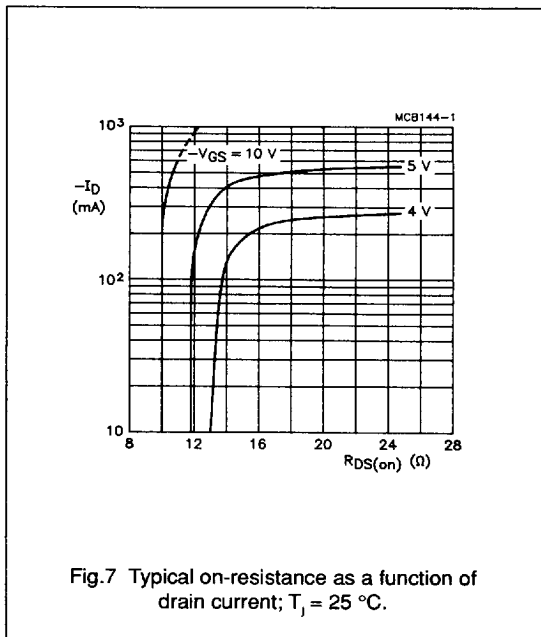
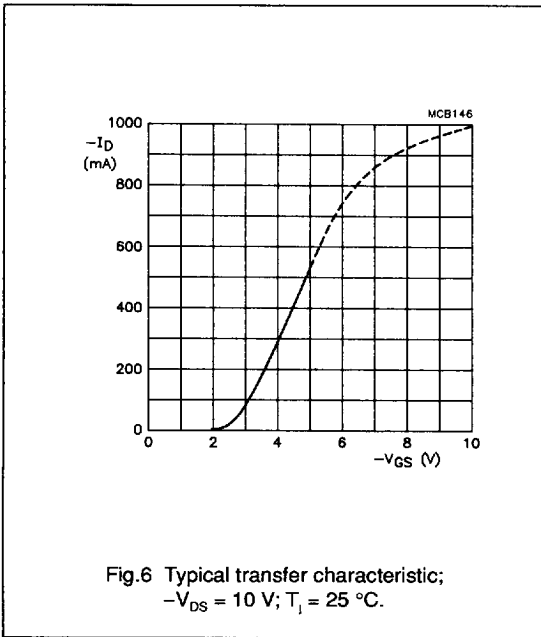
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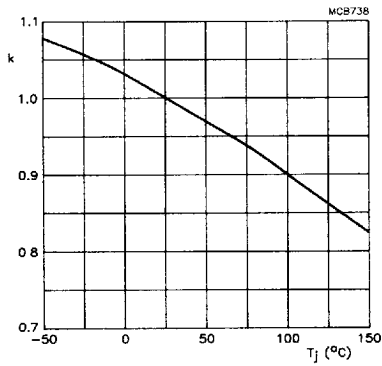
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Fig.10 Temperature coefficient of gate-source
threshold voltage; $k = \frac{V_{GS(th)} \text{ at } T_J}{V_{GS(th)} \text{ at } 25^\circ\text{C}}$; typical
- $V_{GS(th)}$ at -1 mA.